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| GATIONING | | ILING DATE | FIRST NAMED INVENTOR | ATTORNEY DOCKET NO. | CONFIRMATION NO. |
|-------------------------------------|------------|------------|----------------------|-------------------------|------------------|
| APPLICATION NO. 10/802,653 | 03/17/2004 | | Heinz Eisenschmid | 10191/3456 | 3928 |
| 26646 | 7590 | 05/12/2006 | | EXAMINER | |
| KENYON & KENYON LLP ONE BROADWAY | | | | ROGERS, DAVID A | |
| | | | | ART UNIT | PAPER NUMBER |
| NEW YORK | , NY 10004 | | | 2856 | |
| | | | | DATE MAILED: 05/12/2006 | |

Please find below and/or attached an Office communication concerning this application or proceeding.

| | Application No. | Applicant(s) | | |
|---|--|---|--------------------|--|
| | 10/802,653 | EISENSCHMID ET | EISENSCHMID ET AL. | |
| Office Action Summary | Examiner | Art Unit | | |
| | David A. Rogers | 2856 | | |
| The MAILING DATE of this communication Period for Reply | n appears on the cover sheet wit | h the correspondence add | ress | |
| A SHORTENED STATUTORY PERIOD FOR R WHICHEVER IS LONGER, FROM THE MAILIN - Extensions of time may be available under the provisions of 37 C after SIX (6) MONTHS from the mailing date of this communicatic - If NO period for reply is specified above, the maximum statutory p - Failure to reply within the set or extended period for reply will, by Any reply received by the Office later than three months after the earned patent term adjustment. See 37 CFR 1.704(b). | IG DATE OF THIS COMMUNIC FR 1.136(a). In no event, however, may a re on. beriod will apply and will expire SIX (6) MONT statute, cause the application to become ABA | ATION. ply be timely filed I'HS from the mailing date of this con ANDONED (35 U.S.C. § 133). | | |
| Status | | • | | |
| 1) ⊠ Responsive to communication(s) filed on 2a) ⊠ This action is FINAL. 3) □ Since this application is in condition for all closed in accordance with the practice units. | This action is non-final. | • • | ments is | |
| Disposition of Claims | • | | | |
| 4) ⊠ Claim(s) <u>1-4,6-9 and 12-20</u> is/are pending 4a) Of the above claim(s) <u>6-9 and 12-19</u> is 5) □ Claim(s) is/are allowed. 6) ⊠ Claim(s) <u>1-4,11 and 20</u> is/are rejected. 7) □ Claim(s) is/are objected to. 8) □ Claim(s) are subject to restriction a | a/are withdrawn from considerat | ion. | - | |
| Application Papers | | | | |
| 9) The specification is objected to by the Exa 10) The drawing(s) filed on 17 March 2004 is/a Applicant may not request that any objection to Replacement drawing sheet(s) including the co | are: a) accepted or b) objective or b) objective drawing(s) be held in abeyand orrection is required if the drawing(| ce. See 37 CFR 1.85(a). s) is objected to. See 37 CFF | | |
| Priority under 35 U.S.C. § 119 | | | | |
| 12) ☑ Acknowledgment is made of a claim for for a) ☑ All b) ☐ Some * c) ☐ None of: 1. ☑ Certified copies of the priority docur 2. ☐ Certified copies of the priority docur 3. ☐ Copies of the certified copies of the application from the International Books * See the attached detailed Office action for a second content of the application for a second content of the | ments have been received. ments have been received in Ap prionty documents have been ureau (PCT Rule 17.2(a)). | oplication No received in this National S | Stage | |
| Attachment(s) 1) ☑ Notice of References Cited (PTO-892) | A\ ☐ Interview S | ummary (PTO-413) | | |
| Notice of References Cited (PTO-692) Notice of Draftsperson's Patent Drawing Review (PTO-94) Information Disclosure Statement(s) (PTO-1449 or PTO/S Paper No(s)/Mail Date 4/3/06. | 8) Paper No(s | offiniary (F10-413))/Mail Date formal Patent Application (PTO- | 152) | |

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DETAILED ACTION

Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. Claims 1-4, 11, and 20 are rejected under 35 U.S.C. 103(a) as being unpatentable over United States Patent 6,718,819 to Schoess as applied to claim 1, and further in view of United States Patent Application Publication 2003/0062008 to Gramkow *et al.*

As shown in figures 2 and 3 the device of Schoess comprises a sensor (reference item 115) having a structured metal layer in the form of interdigital electrodes (reference items 137 and 139) that measures the dielectric of oil in an engine. The sensor is formed by a providing a metal structure on a nonconductive polymeric substrate (reference item 134). Official notice is hereby taken that plastics are known nonconductive polymeric materials. As the applicant did not timely traverse the prior assertion of official notice that the common knowledge or well-known in the art statement is taken to be admitted prior art.

The sensor is a capacitive sensor that can be used to detect the dielectric value of the oil. The sensor is provided on the inner surface of a

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housing (reference item 111). The system also has a base member (reference item 14) that forms a cover to fit with the housing. This combination shields the sensor against disturbances. The housing has at least one inlet to allow oil into the housing.

Schoess teaches the claimed invention except for a recitation of manufacturing the sensor as a molded interconnect device. Gramkow *et al.*, however, teaches the benefits of molded interconnect devices. See, for example, paragraph 0009.

It would have been obvious to one of ordinary skill in the art at the time of the invention to modify the teachings of Schoess with the teachings of Gramkow *et al.* to provide a sensor manufactured using molded interconnect device techniques in order to save space and materials thus making the sensor smaller.

Response to Arguments

3. Applicant's arguments filed 27 March 2006 have been fully considered but they are not persuasive.

In response to applicant's argument that the references fail to show certain features of applicant's invention, it is noted that the features upon which applicant relies; i.e., a separate sensor in an oil pan that can be easily replaced, are not recited in the rejected claim(s). Although the claims are interpreted in light of the specification, limitations from the specification are

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not read into the claims. See *In re Van Geuns*, 988 F.2d 1181, 26 USPQ2d 1057 (Fed. Cir. 1993).

The applicant appears to argue that Gramkow et al. does not teach a sensor element formed using MID technology. However, Gramkow et al. was not relied upon for a sensor. Gramkow et al. teaches that MID production technologies are beneficial in creating electrical circuits that save space and expense. Furthermore, the sensor in figure 2 of Schoess clearly shows a three-dimensional sensor structure; i.e., a sensor that is placed about the inner surface of the housing. This sensor would benefit from MID technology since the expenses of a separate mounting device could be eliminated and since MID technology could be used to simultaneously create the connecting circuit (reference items 106 and 108).

Conclusion

4. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.

<u>"Molded Interconnect Devices Reshape Electromechanical Design"</u>, clearly teaches the benefits of MID:

Nevertheless, for products with some degree of electromechanical complexity, MID technology is economically competitive. Unlike pc boards, which are typically limited to two-dimensional planes, MIDs can implement three-dimensional circuitry. Among other things, a circuit pattern with multiple planes allows better spacing of circuitry, as well as the connected switches and buttons.

Furthermore, MIDs can reduce component count and cost by embedding features such as a connector, a wire harness, or a lamp holder within the device. At the same time, MIDs can be designed to be self-supporting, thereby eliminating the additional

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mechanical parts required to support pc boards. By reducing the required number of

parts, MIDs save space and shorten assembly time.

<u>United States Patent 4,241,384</u> clearly shows a housing formed of

nonconductive plastic polymeric materials.

5. Any inquiry concerning this communication or earlier communications

from the examiner should be directed to David A. Rogers whose telephone

number is (571) 272-2205. The examiner can normally be reached on Monday

- Friday (0730 - 1600). If attempts to reach the examiner by telephone are

unsuccessful, the examiner's supervisor, Hezron E. Williams can be reached on

(571) 272-2208. The fax phone number for the organization where this

application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from

the Patent Application Information Retrieval (PAIR) system. Status information

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http://pair-direct.uspto.gov. Should you have questions on access to the

Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-

9197 (toll-free).

HEZRON WILLIAMS

SUPERVISORY PATENT EXAMINER

TECHNOLOGY CENTER 2800